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# FOD819 Series

## FOD819 4-Pin DIP High Speed Phototransistor Optocouplers

### Description

The FOD819 consists of a gallium arsenide (GaAs) infra-red emitting diode, driving a high speed photo detector with integrated base-to-emitter resistor,  $R_{BE}$ , in a 4-pin dual-in-line package. It is designed to be an improved replacement to the popular FOD817 Series when higher speed performance is required in isolated data signal transmission.

### Features

- High Speed Performance ~ 30 kHz
- Current Transfer Ratio: 100% to 600%
- Minimum  $BV_{CEO}$  of 80 V Guaranteed
- Safety and Regulatory Approvals:
- UL1577, 5,000  $VAC_{RMS}$  for 1 Minute
- DIN EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

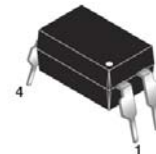
### Typical Applications

- Digital Logic Inputs
- Microprocessor Inputs
- Power Supply Monitor
- Twisted Pair Line Receiver
- Telephone Line Receiver



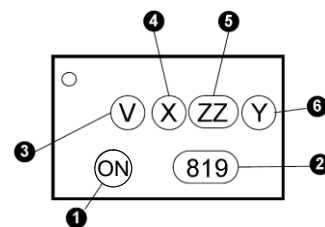
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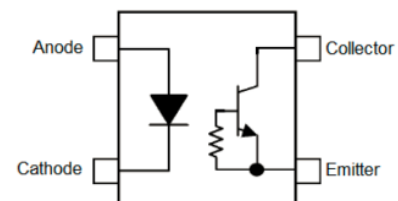
DIP 4 PINS

### MARKING DIAGRAM



1. ON = Company Logo
2. 819 = Device Number
3. V = DIN EN/IEC60747-5-5 Option
4. X = One-Digit Year Code
5. ZZ = Digit Work Week
6. Y = Assembly Package Code

### PIN CONNECTIONS



### ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

# FOD819 Series

## Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

**Table 1. SAFETY AND INSULATION RATINGS**

Parameter		Characteristics
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	< 150 V <sub>RMS</sub>	I-IV
	< 300 V <sub>RMS</sub>	I-III
Climatic Classification		55/115/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

**Table 2.**

Symbol	Parameter	Value	Unit
V <sub>PR</sub>	Input-to-Output Test Voltage, Method A, V <sub>IORM</sub> × 1.6 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC	1360	V <sub>peak</sub>
	Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> × 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
V <sub>IORM</sub>	Maximum Working Insulation Voltage	850	V <sub>peak</sub>
V <sub>IOTM</sub>	Highest Allowable Over-Voltage	8000	V <sub>peak</sub>
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option W, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.4	mm
T <sub>S</sub>	Case Temperature (Note 1)	175	°C
I <sub>S,INPUT</sub>	Input Current (Note 1)	400	mA
P <sub>S,OUTPUT</sub>	Output Power (Note 1)	700	mW
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V (Note 1)	> 10 <sup>11</sup>	Ω

1. Safety limit values – maximum values allowed in the event of a failure.

**Table 3. ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
<b>TOTAL PACKAGE</b>			
T <sub>STG</sub>	Storage Temperature	-55 to +125	°C
T <sub>OPR</sub>	Operating Temperature	-55 to +110	°C
T <sub>J</sub>	Junction Temperature	-55 to +125	°C
T <sub>SOL</sub>	Lead Solder Temperature	260 for 10 seconds	°C
θ <sub>JC</sub>	Junction-to-Case Thermal Resistance	210	°C/W
P <sub>TOT</sub>	Total Device Power Dissipation	200	mW
<b>EMITTER</b>			
I <sub>F</sub>	Continuous Forward Current	50	mA
V <sub>R</sub>	Reverse Voltage	6	V
P <sub>D</sub>	Power Dissipation	70	mW
	Derate Above 100°C	1.7	mW/°C

# FOD819 Series

**Table 3. ABSOLUTE MAXIMUM RATINGS** (continued)

Symbol	Parameter	Value	Unit
<b>DETECTOR</b>			
$V_{CEO}$	Collector–Emitter Voltage	80	V
$V_{ECO}$	Emitter–Collector Voltage	2	V
$I_C$	Continuous Collector Current	30	mA
$P_C$	Collector Power Dissipation	150	mW
	Derate Above 90°C	2.9	mW/°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## Electrical Characteristics

**Table 4. INDIVIDUAL COMPONENT CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>EMITTER</b>						
$V_F$	Forward Voltage	$I_F = 1.5\text{ mA}$		1.2	1.4	V
$I_R$	Reverse Current	$V_R = 4.0\text{ V}$			10	$\mu\text{A}$
$C_t$	Terminal Capacitance	$V = 0, f = 1\text{ kHz}$		30		pF

### DETECTOR

$I_{CEO}$	Collector Dark Current	$V_{CE} = 40\text{ V}, I_F = 0$			100	nA
$BV_{CEO}$	Collector–Emitter Breakdown Voltage	$I_C = 0.1\text{ mA}, I_F = 0$	80	150		V
$BV_{ECO}$	Emitter–Collector Breakdown Voltage	$I_E = 0.1\text{ mA}, I_F = 0$	2	7		V

### DC TRANSFER CHARACTERISTICS

CTR	Current Transfer Ratio (Note 2)	$I_F = 1.5\text{ mA}, V_{CE} = 5\text{ V}$	100		600	%
$V_{CE(SAT)}$	Saturation Voltage	$I_F = 1.5\text{ mA}, I_C = 0.2\text{ mA}$			0.3	V
$I_{C(OFF)}$	OFF–state collector current	$V_F = 0.7\text{ V}, V_{CE} = 40\text{ V}$			10	$\mu\text{A}$

### AC TRANSFER CHARACTERISTICS

$t_R$	Rise Time (Saturated)	$I_F = 1.5\text{ mA}, V_{CC} = 5\text{ V}, R_L = 10\text{ k}\Omega$ (Note 3)		12		$\mu\text{s}$
$t_F$	Fall Time (Saturated)			20		$\mu\text{s}$
$t_{PHL}$	Propagation Delay Time High–to–Low	$I_F = 1.5\text{ mA}, V_{CC} = 5\text{ V}, R_L = 10\text{ k}\Omega$ (Note 3)		9	30	$\mu\text{s}$
$t_{PLH}$	Propagation Delay Time Low–to–High			18	30	$\mu\text{s}$

- Current Transfer Ratio (CTR) =  $I_C / I_F \times 100\%$ .
- Refer to test circuit setup.

**Table 5. ISOLATION CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{ISO}$	Input–Output Isolation Voltage (Note 4)	$f = 60\text{ Hz}, t = 1\text{ minutes},$ $I_{I-O} \leq 2\text{ }\mu\text{A}$	5000			$V_{AC_{RMS}}$
$R_{ISO}$	Isolation Resistance	$V_{I-O} = 500\text{ V}_{DC}$		$1 \times 10^{11}$		$\Omega$
$C_{ISO}$	Isolation Capacitance	$V_{I-O} = 0, f = 1\text{ MHz}$		0.6	1.0	pf

- For this test, Pins 1 and 2 are common, and Pins 3 and 4 are common.

Typical Performance Curves

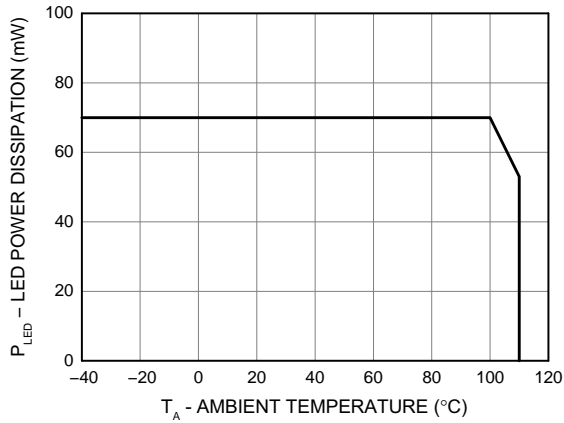


Figure 1. LED Power Dissipation vs. Ambient Temperature

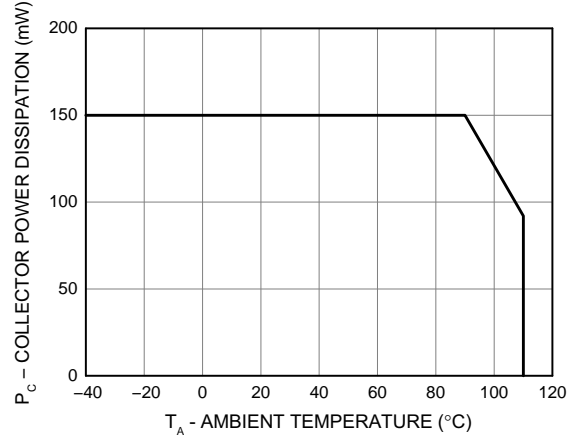


Figure 2. Collector Power Dissipation vs. Ambient Temperature

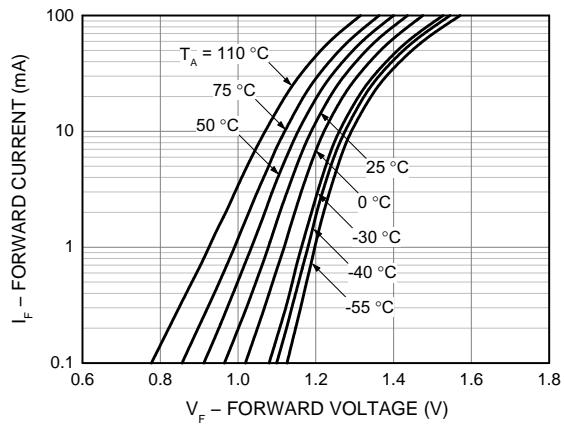


Figure 3. Forward Current vs. Forward Voltage

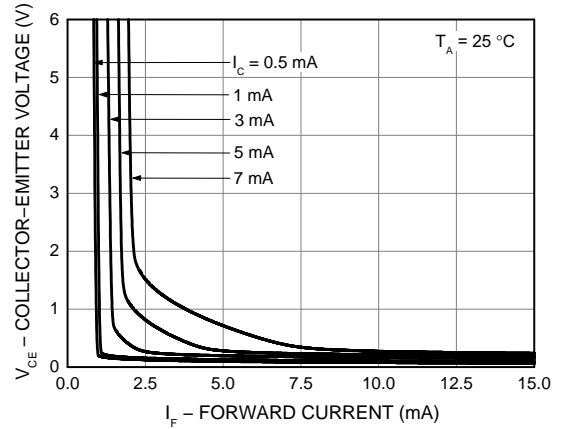


Figure 4. Collector-Emitter Voltage vs. Forward Current

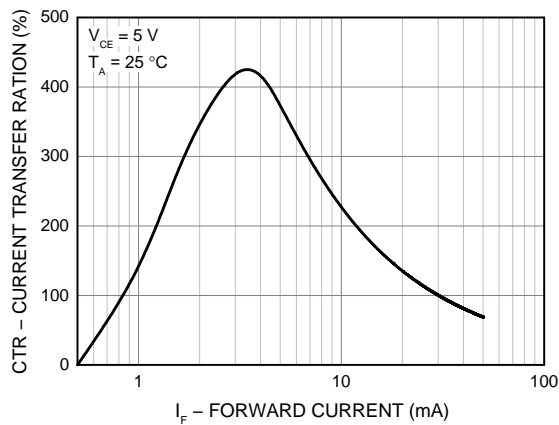


Figure 5. Current Transfer Ratio vs. Forward Current

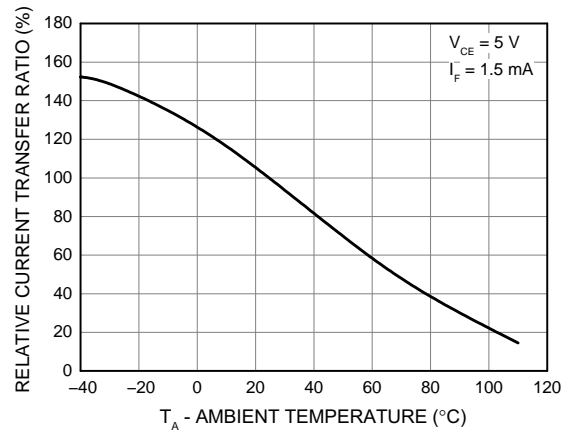
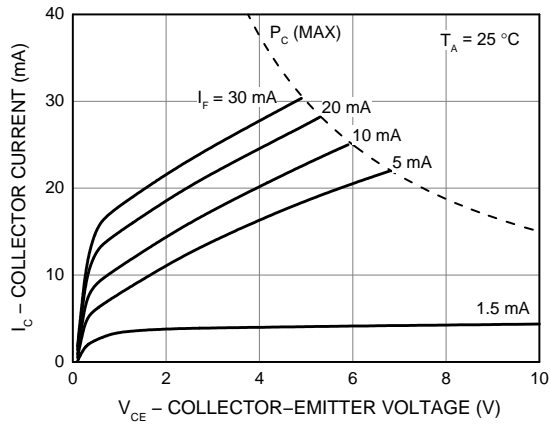
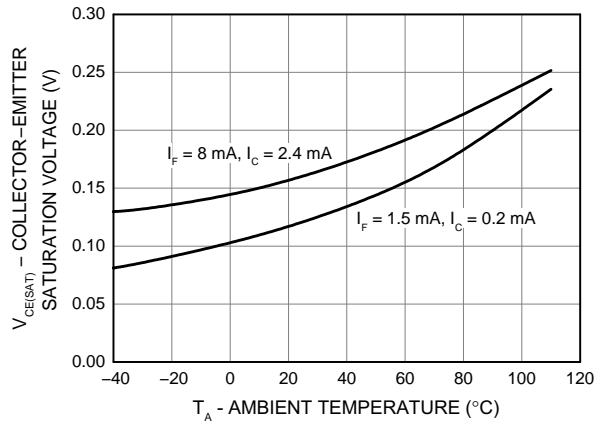


Figure 6. Relative Current Transfer Ratio vs. Ambient Temperature

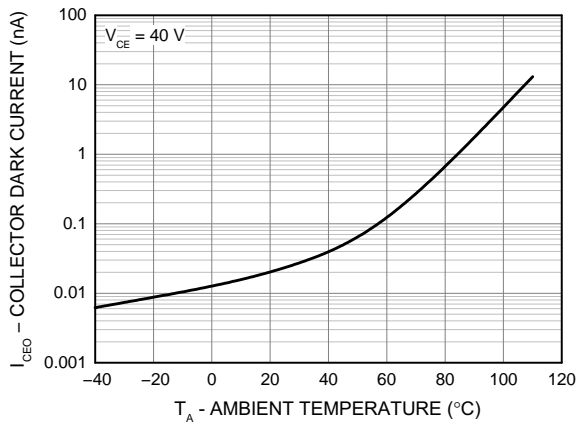
# FOD819 Series



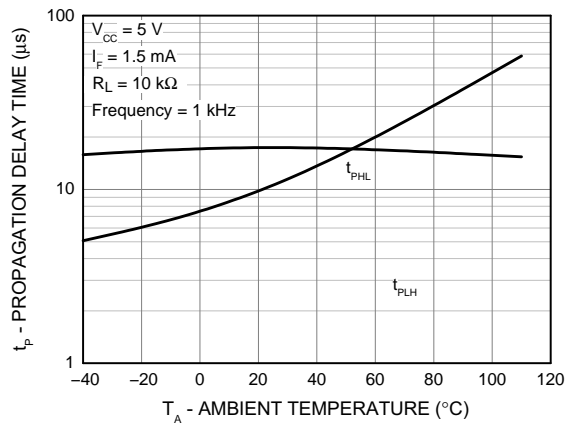
**Figure 7. Collector Current vs. Collector-Emitter Voltage**



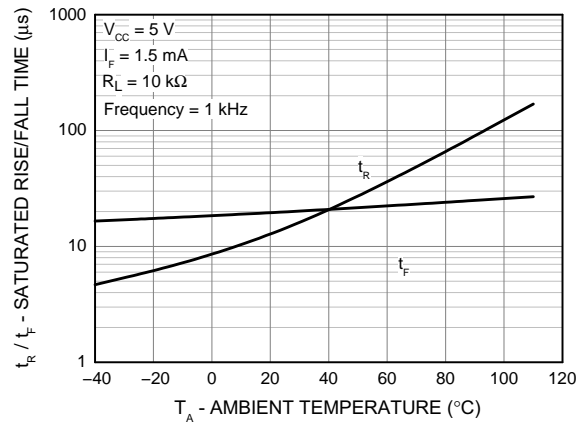
**Figure 8. Collector-Emitter Saturation Voltage vs. Ambient Temperature**



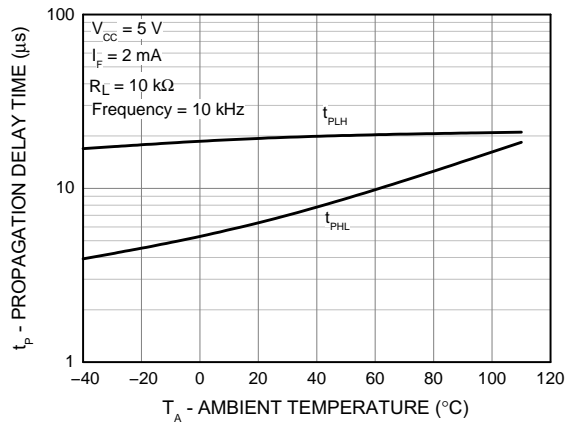
**Figure 9. Collector Dark Current vs. Ambient Temperature**



**Figure 10. Propagation Delay vs. Ambient Temperature**

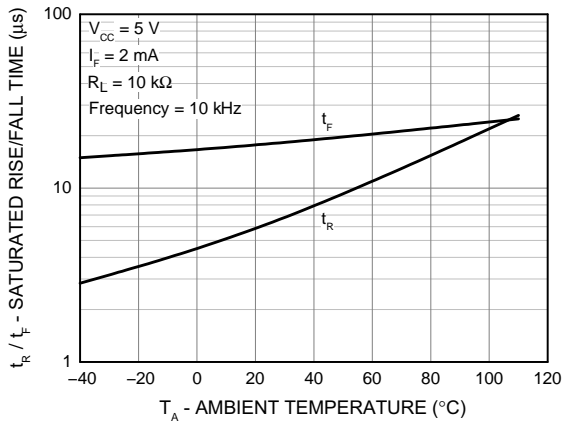


**Figure 11. Saturated Rise / Fall Time vs. Ambient Temperature**

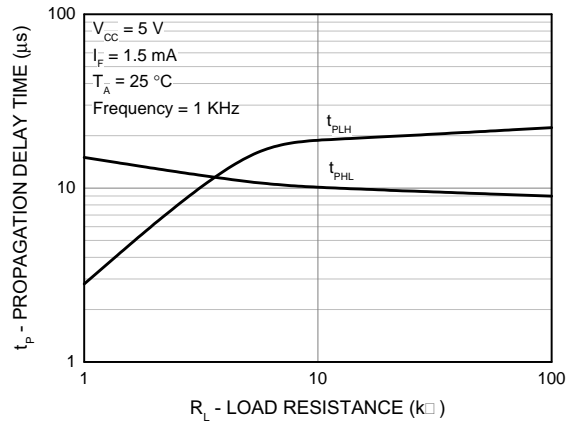


**Figure 12. Propagation Delay vs. Ambient Temperature**

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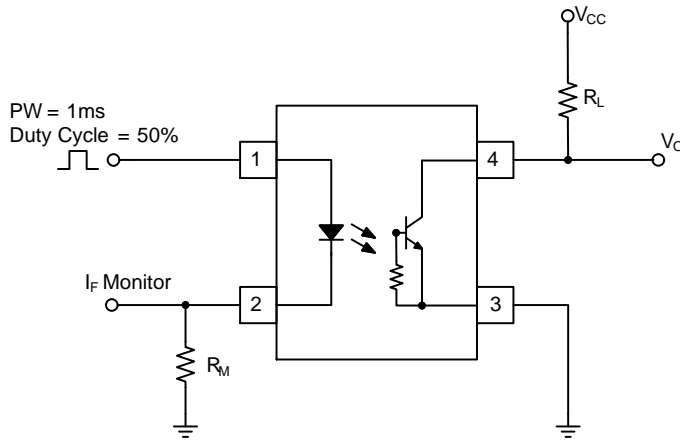


**Figure 13. Collector Dark Current vs. Ambient Temperature**

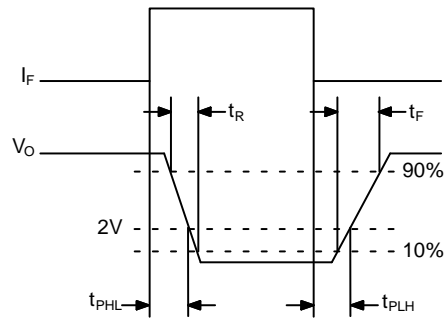


**Figure 14. Propagation Delay vs. Ambient Temperature**

## Test Circuit



**Figure 15. Test Circuit for Response Time**



**Figure 16. Timing Diagram**

# FOD819 Series

## Reflow Profile

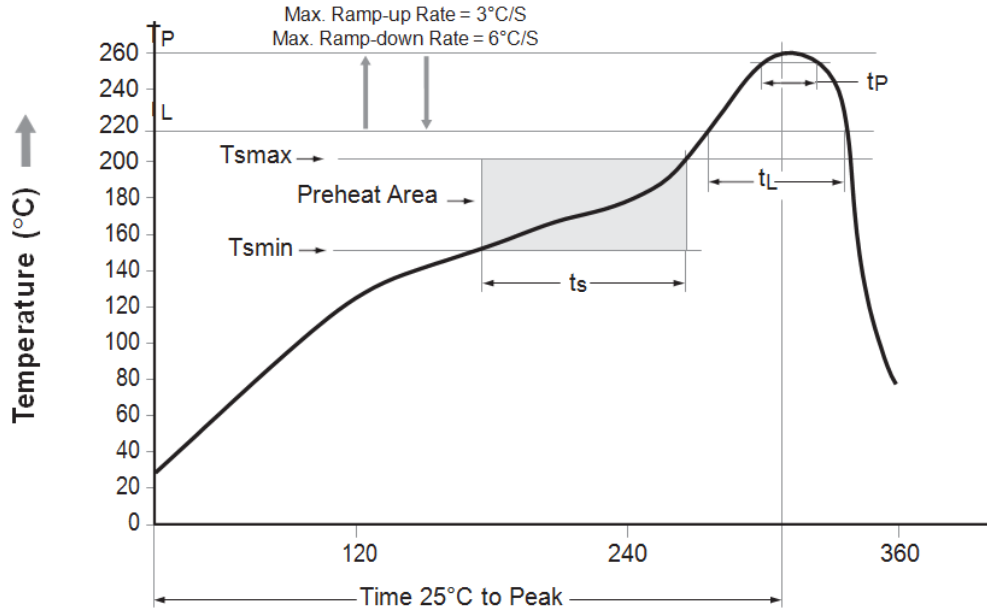


Figure 17. Reflow Profile

Table 6.

Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub> Amin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub> Amin</sub> to T <sub>smax</sub> )	60–120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>p</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60–150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>p</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Table 7. ORDERING INFORMATION

Part Number	Package	Packing Method †
FOD819	DIP 4-Pin	Tube (100 units per tube)
FOD819S	SMT 4-Pin (Lead Bend)	Tube (100 units per tube)
FOD819SD	SMT 4-Pin (Lead Bend)	Tape and Reel (1,000 units per reel)
FOD819300	DIP 4-Pin, DIN EN/IEC60747-5-5 option	Tube (100 units per tube)
FOD8193S	SMT 4-Pin (Lead Bend), DIN EN/IEC60747-5-5 option	Tube (100 units per tube)
FOD8193SD	SMT 4-Pin (Lead Bend), DIN EN/IEC60747-5-5 option	Tape and Reel (1,000 units per reel)
FOD819300W	DIP 4-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 option	Tube (100 units per tube)

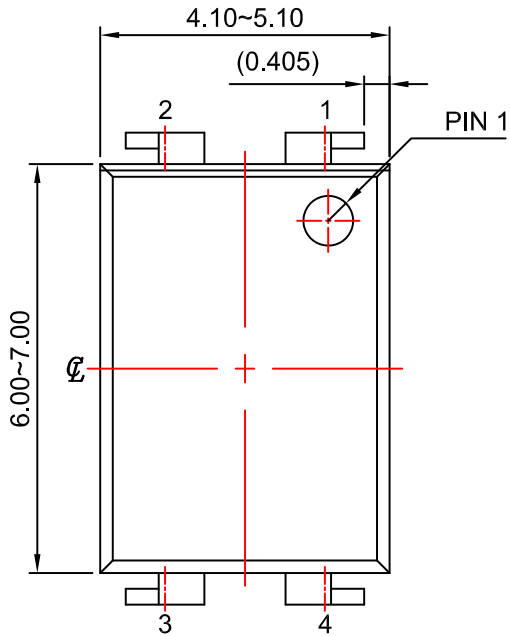
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



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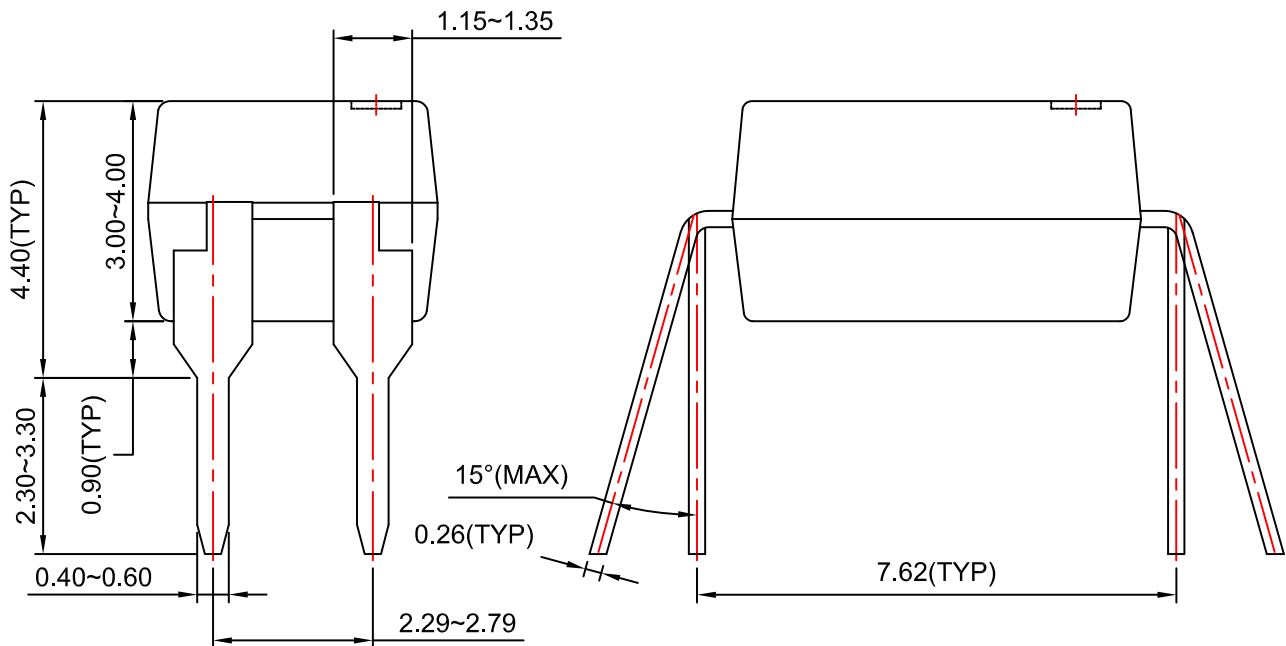
## PACKAGE DIMENSIONS

PDIP4 4.6 x 6.5, 2.54P  
CASE 646CD  
ISSUE O



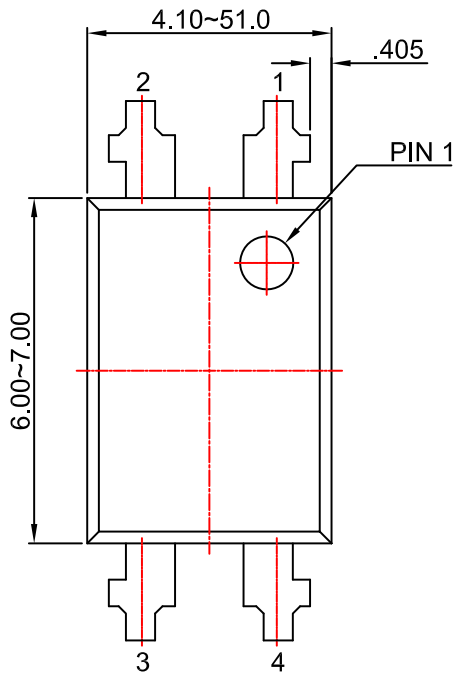
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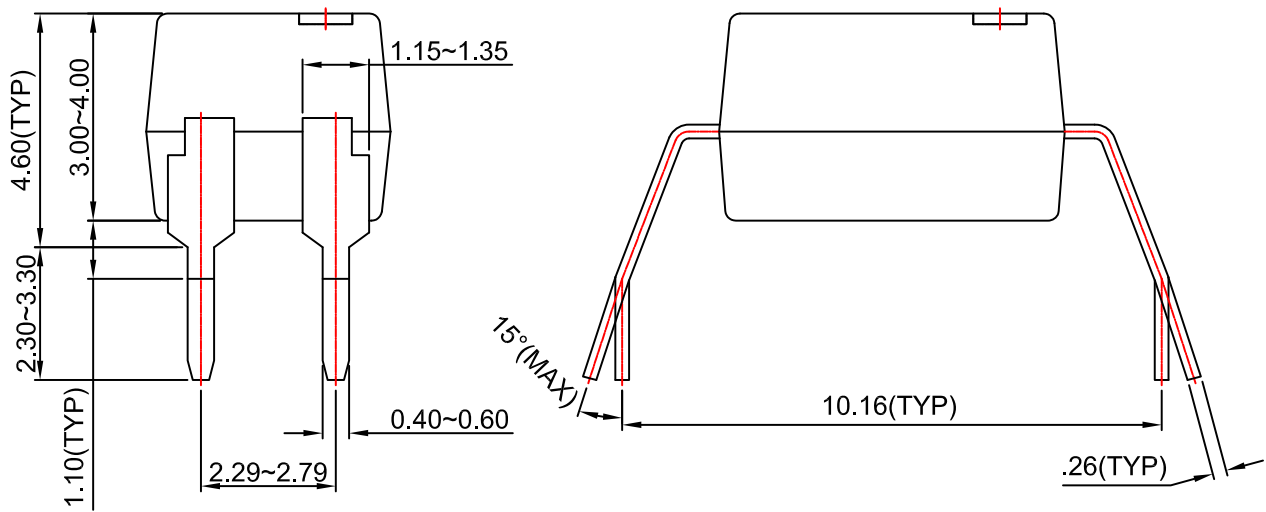
# FOD819 Series

PDIP4 4.6 x 6.5, 2.54P  
CASE 646CA  
ISSUE O



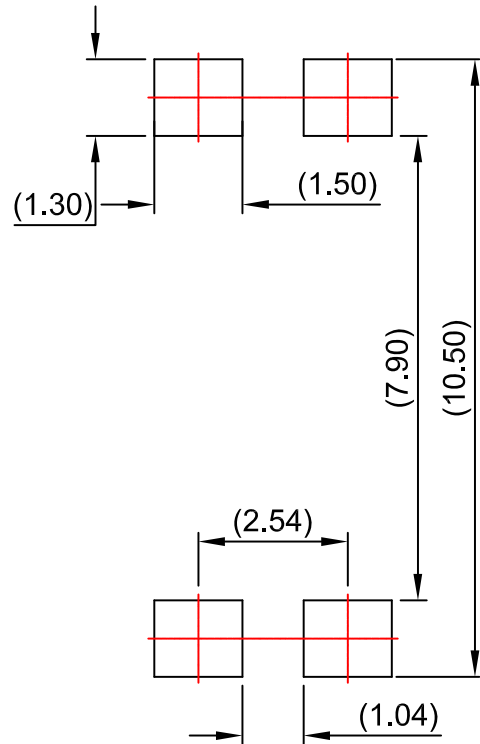
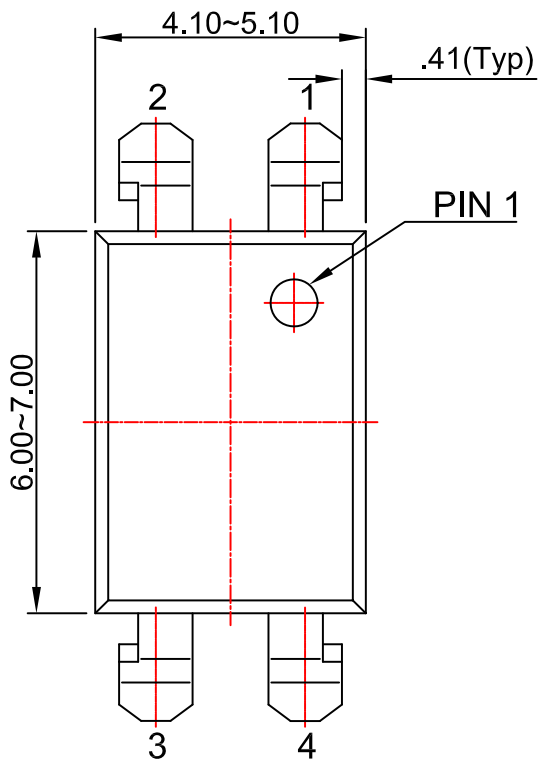
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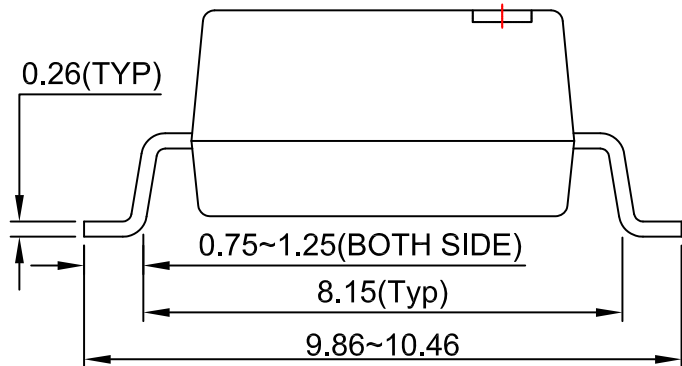
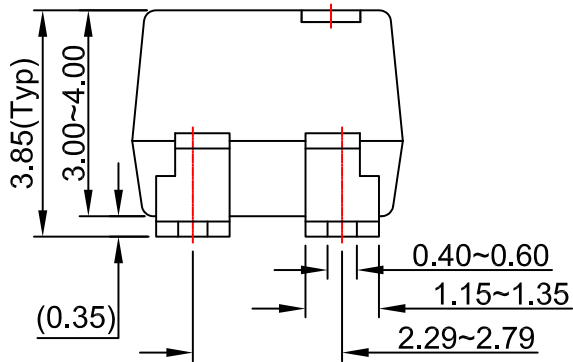


# FOD819 Series

PDIP4 GW  
CASE 709AH  
ISSUE A




LAND PATTERN RECOMMENDATION



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